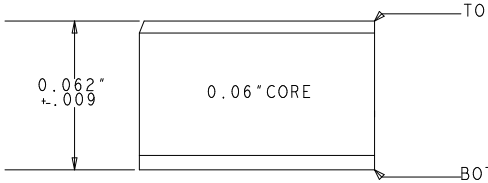
NOTES:UNLESS OTHERWISE SPECIFED

1. COMPLIANCE.
   A. THE PCB SHALL MEET ROHS (LEAD FREE) STANDARDS.
   B. THE PCB SHALL MEET IPC-6012 CLASS 2 REQUIREMENTS.
2. MATERRIAL.
   A BASE LAMINATE. ISOLA 370HR OR EQUIVALENT WITH A THERMAL RESISTACE OF 260 DEGREES C OR HIGER FOR ROHS COMPLINACE.
   B BONDING MATERIAL. PRE-IMPREGNATED PER IPC-4101/24 (TYPE GFG) WITH MINIMUM Tg 150 AND Td 325.
3. FINISH.
   A. ELECTROLESS NICKEL / IMMERSION GOLD (ENIG).
   B. NICKEL SHALL BE A MINIMUM OF 118 MICRO INCHES.
   C GOLD SHALL BE A MINIMUM OF 2 MICRO INCHES.
4. HOLE DRILLING:
   ALL HOLES TO BE WITHIN.003" OF TRUE POSTIO.
5. PLATING;
   ALL PLATED HOLDS SHALL HAVE A MINIMUM WALL THICKNESS OF .0007" COPPER. ALL HOLE DIAMETERS ARE AFTER PLATIN. ALL ANNULAR RINGS SHAALL BE .002" OR GREATER.
6. SOLDERMASK- LIQUID PHOTO IMAGEABLE OVER BARE COPPER COLOR BLACK MATTE TO BE APPLIED TO BOTH SIDES ACCORDING TO IPC-SM-840C.
7. SILKSCEEN - SHELL BE WHITE BASE EPOXY PAINT TO BE APPLIED TO BOTHE SIDES. THERE SHALL BE NO SILKSCREEN ON ANY EXPOSED PADS.
8. THIEVING - THIEVING MAY BE ADDED TO COMPENSATEFOR LOW COPPER DENSITY THIEVING SHALL NOT BE ADDED TO WITHIN 3.8mm MINIMUM DISTANCE TO ANY EXISTING FEATURE. THERE SHALL BE NO EXPOSED THIEVING.
9. PCB VENDOR SHALL PROVIDE, CERTIFICATE OF CONFORMANCE.
10. PCB VENDOR INDENTIFICATION, DATE CODE, UL CODE (94V-0) AND UR SYMBOL TO BE MARKED USING SILKCREEN ON THE TOP SIDE. (OR BOTTOM SIDE IF NEED BE)
11. ELECTRICIAL TEST - BOARDS SHALL BE ELECTICALLY TESTED FOR COMTINUITY AND ISOLATION IN ACCORRDACE WITH IPC-6012. AN IPC-365 NETLIST FILE IS PROVIDED. EXCEPTIONS TO THE INTEGRITY OF THE ELECTRICAL TEST ARE AS FOLLOWS:
    INTERTIONAL SHORTS: NONE
    INTERTIONAL OPENS: NONE
12. CONTROLLED DIELECTRIC-THE DIELECTRIC THICKNESS FOR EACH LAYER. SHALL BE AS PRESCRIBED IN THE LAYERRING DETAIL SHOWN BELOW.
13. EXPOSED COPPER - THER SHAL BE NO EXPOSED COPPER.
14. PCB manufacturing and assembly to be according to data files shown in Gerber file table listed in bare board drawing.

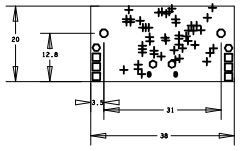
CONTROLLED DIELECTRIC [12]

LAYERING DETAIL
SCALE=NONE



LAYER	FINISHED COPPER WEIGHT
SILK SCREEN SOLDER MASK TOP SIDE	1.0 OZ
BOTTOM SIDE SOLDER MASK	1.0 OZ

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	0.254	+0.03/-0.03	PLATED	50
□	0.9144	+0.03/-0.03	PLATED	6
o	0.9144	+0.03/-0.03	PLATED	2
o	1.016	+0.03/-0.03	PLATED	2
o	3.0	+0.03/-0.03	PLATED	2
•	1.3208x0.762	+0.03/-0.03	PLATED	2



Design History
REV A - Initial Release
Rev B - Add pullup to U1-11, move R8, Move FB3 and R9 Silk.

ENGINEER: Scott Jenney	DRAWN BY: Scott Jenney	BOARD NUMBER: ISLI2UEV1Z Intersil Corporation 1001 MURPHY RANCH RD MILPITAS CA 95035
RELEASED BY:	DATE DRAWN: April 16, 2016	
UPDATED BY:	DATE RELEASES:	
intersil	DATE UPDATED:	MASK#: HDWR ID: REV: B
	FILENAME: Microcontroller Interface Board	